

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

E	BC-13-0004449	C.S Li	REV.	ECN. NO.	APPD.
F	BC-13-0087028	C.S Li	A	BC-10-0098922	Herry Yang
G	BC-14-0008133	C.S Li	B	BC-11-0038746	Herry Yang
			C	BC-11-0049175	Herry Yang
			D	BC-11-0119959	Herry Yang

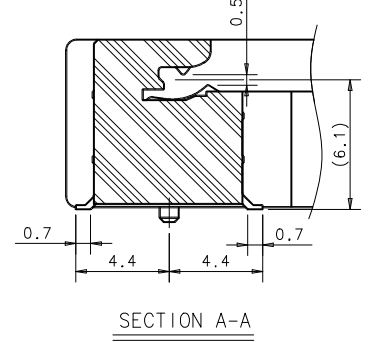
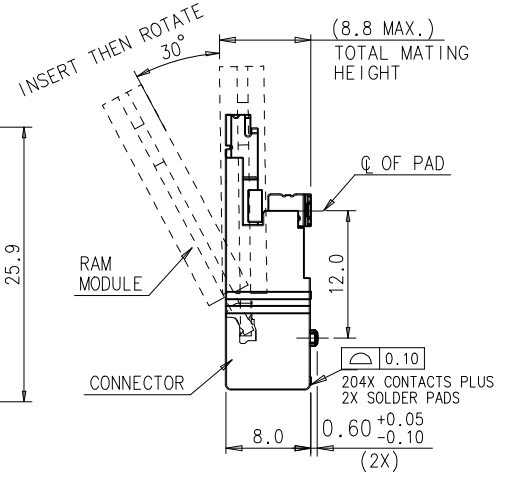
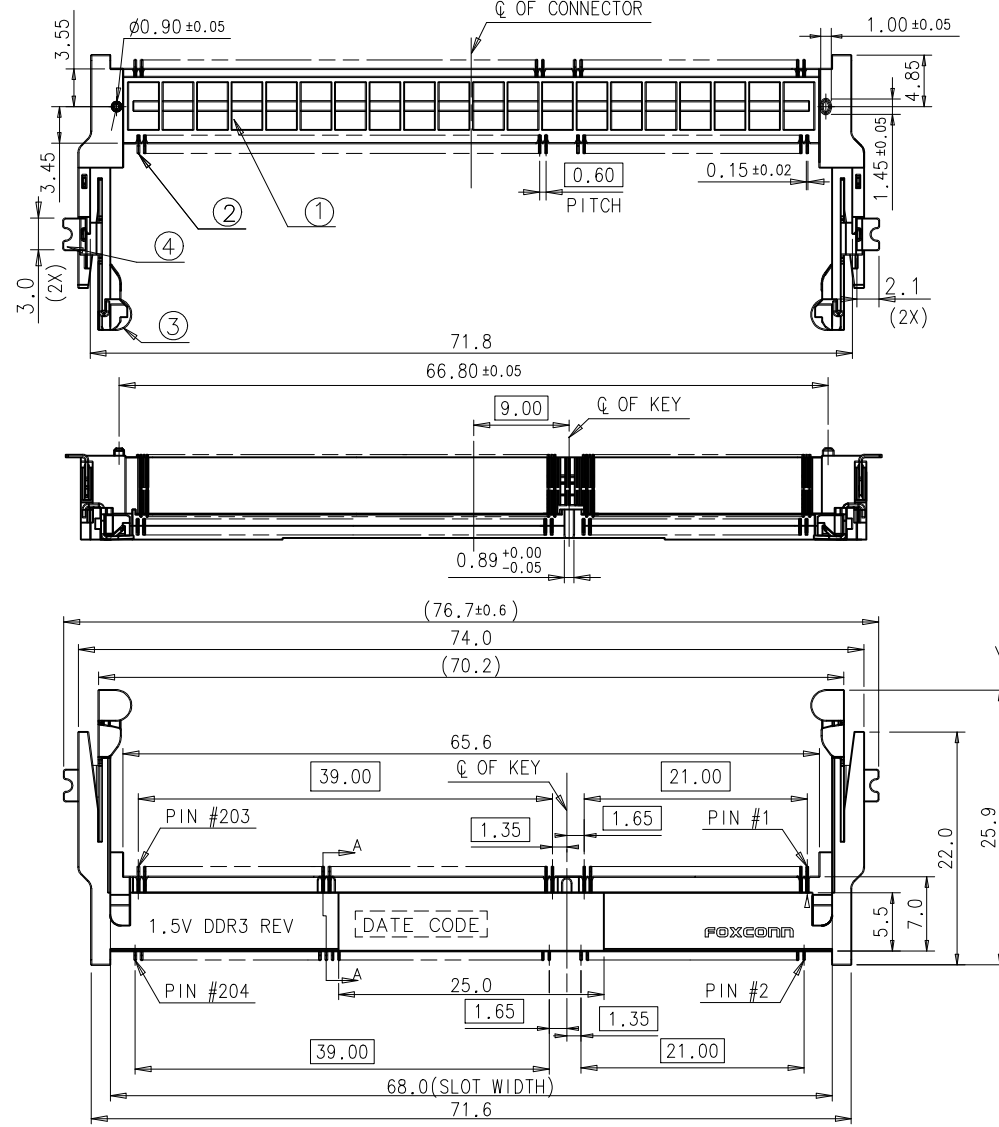
- NOTES:
- ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.  
(PER PIN) DOESN'T EXCEED 30°C ABOVE AMBIENT AT 0.5 AMPERE MAX. PER PIN.
    - VOLTAGE RATING: 25V AC.
    - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
    - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz, FOR 1 MINUTE.
    - CONTACT RESISTANCE: 50 MILLIOHMS MAX. PER PIN INITIAL.  
60 MILLIOHMS MAX. PER PIN AFTER FULL ENVIRONMENTAL TESTING.
  - MECHANICAL CHARACTERISTICS: DURABILITY: 60 MATING CYCLES.
  - OPERATION TEMPERATURE: -55°C TO +85°C.
  - RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260°C, 10\*20S.
  - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAIL & AVAILABILITY.

PART NO. DESCRIPTION: A S O A6 2 \* - H 8 R N - \* H

MEMORY MODULE SOCKET  
HORIZONTAL TYPE  
SINGLE ROW  
NO. OF POS.  
A6 = 204 POS.  
SMT

CONTACT AREA PLATING  
1-GOLD FLASH  
Y=5u\* GOLD PLATING  
6=10u\* GOLD PLATING  
7=15u\* GOLD PLATING  
3=30u\* GOLD PLATING

H=HALOGEN FREE & LEAD FREE  
4=SOFT TRAY  
7=TAPE REEL  
N=GENERAL TYPE  
R=REVERSE  
8=8.0mm HEIGHT  
DDR CONNECTOR



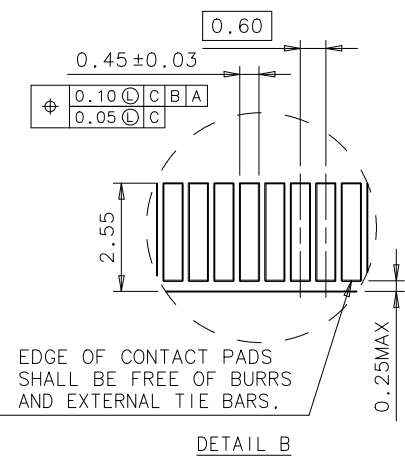
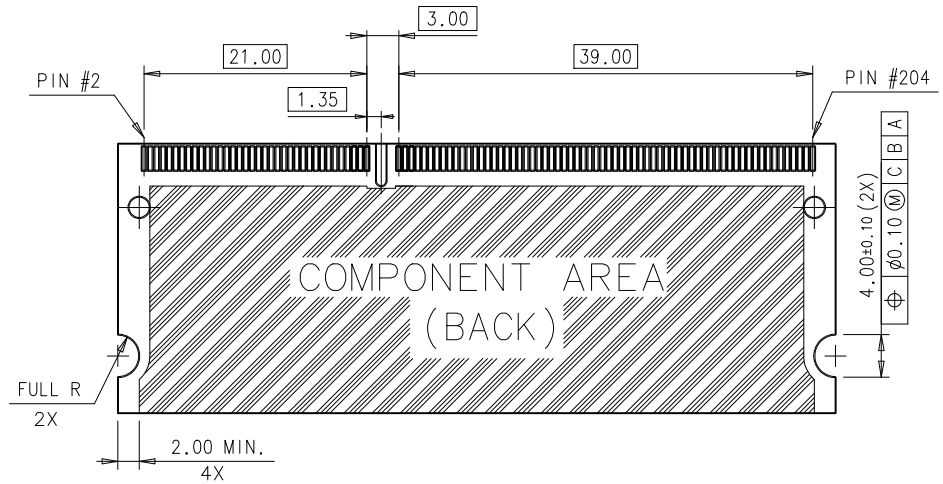
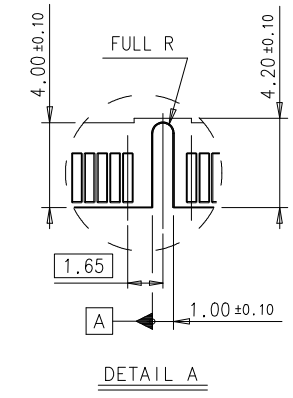
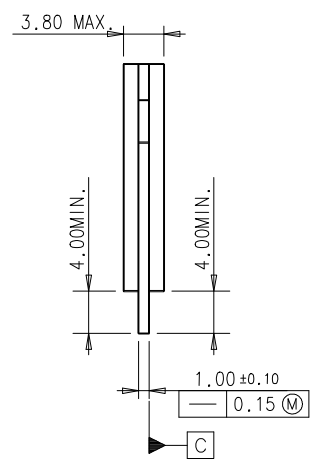
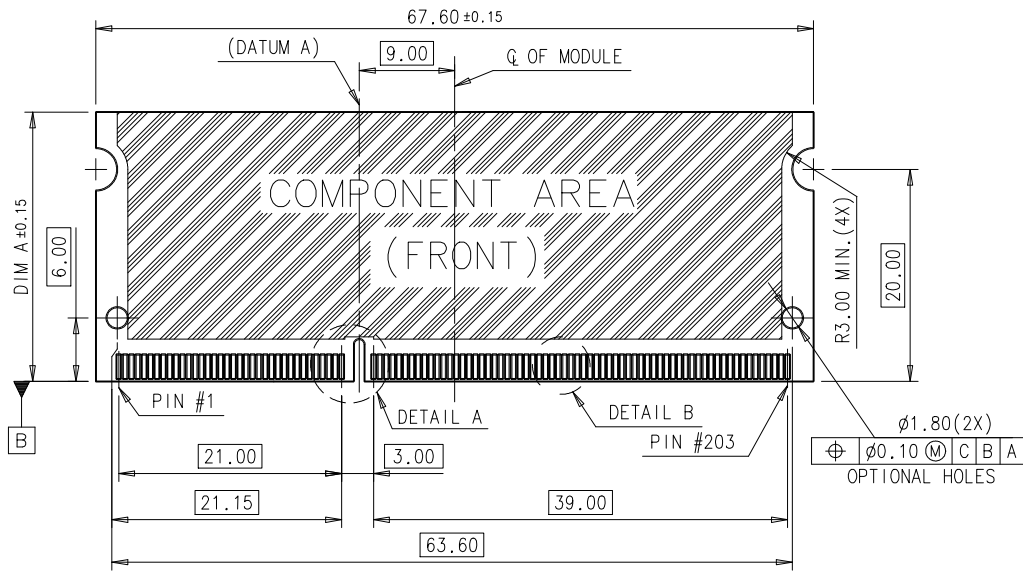
ITEM	DESCRIPTION	Q'TY	MATERIAL	TREATMENT
④	METAL PAD	2	COPPER ALLOY	50u* NICKEL UNDER PLATING OVER ALL 2u* Pd PLATING OVER SOLDER AREA
③	METAL SPRING	2	COPPER ALLOY	50u* NICKEL PLATING OVER ALL
②	CONTACT	204	COPPER ALLOY	50u* NICKEL UNDER PLATING GOLD FLASH AT TAIL GOLD FLASH OR 5u* OR 10u* OR 15u* OR 30u* GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, HALOGEN-FREE, IVORY COLOR

X. ± 0.30	X° ±	UNITS	mm	NAME (INTENDED USE)	<b>FOXCONN®</b>	
.X ± 0.25	.X° ±	MAT'L		DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.	
.XX ± 0.15	.XX° ±			PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL	
.XXX ±	.XXX° ±	FINISH		ASOA62*-H8RN-*H	TITLE: CUSTOMER DRAWING	
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				CHKD:	ZH Wang	
				DR:	Wang Justin 2/24'14	
				DWG NO.: 317-0000-1997		
				SCALE	SHEET	REV.
				N/A	1/5	G

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.

A  
B  
C  
D  
E



DDR III SO-DIMM MODULE BOARD LAYOUT

SDRAM VARIATIONS	DIM A
TYPE 1	25.40
TYPE 2	31.75
TYPE 3	30.00

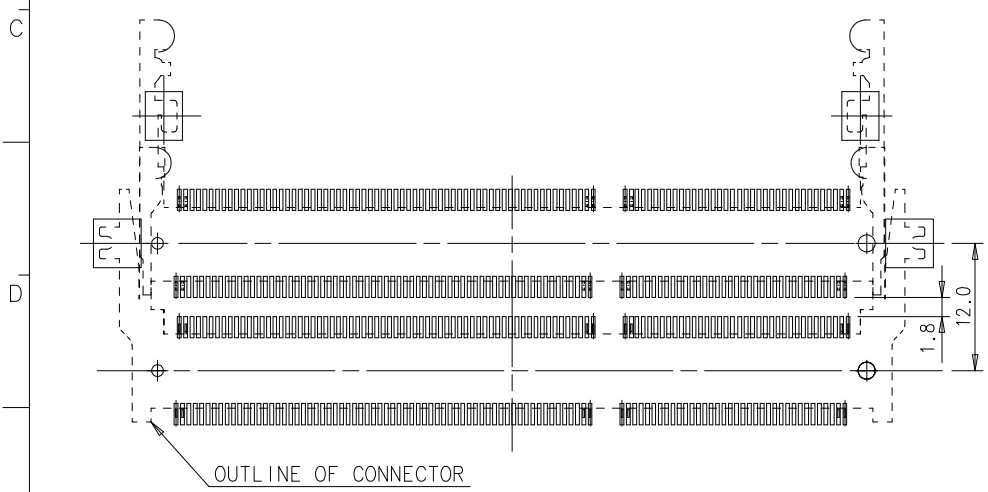
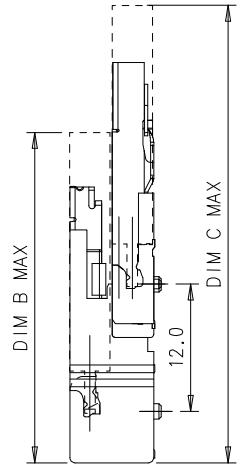
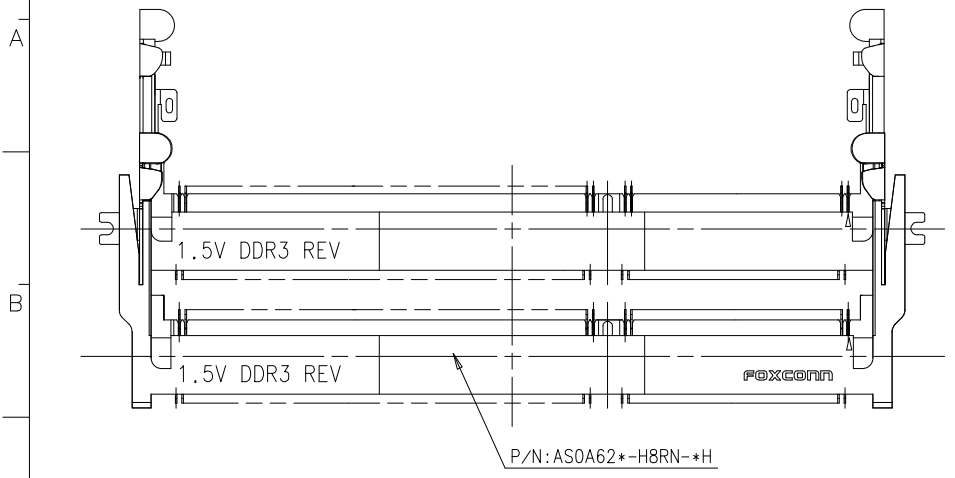
X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 0.10	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.05	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □ CONFIDENTIAL □ SECRET ■ GENERAL
.XXX ±	.XXX° ±		ASOA62*-H8RN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1997
Q'TY			DR: Wang Justin 2/24/14	SCALE SHEET REV.
				N/A 2/5 G

A  
B  
C  
D  
E

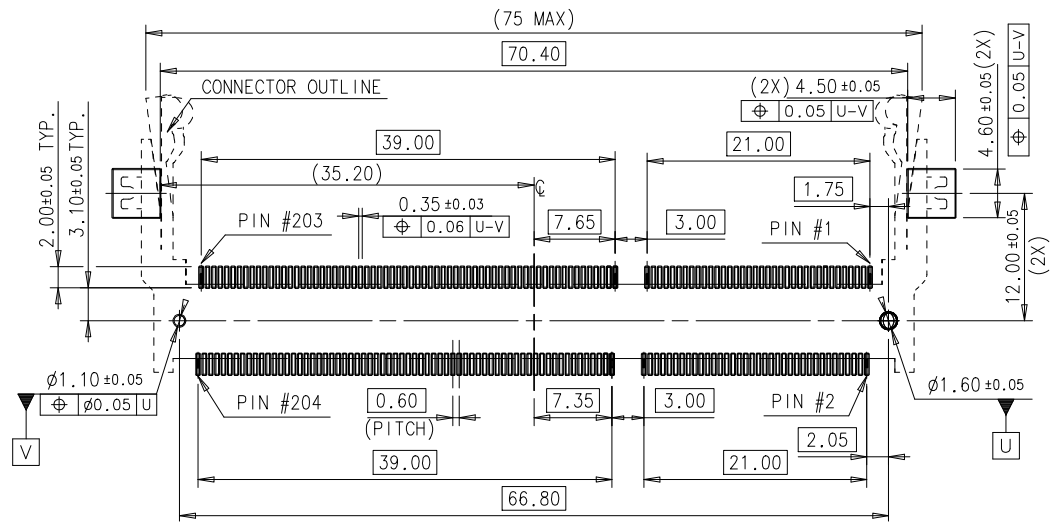
1 2 3 4 5 6 7 8

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



P.C.B. LAYOUT (STACKED ORIENTATION)



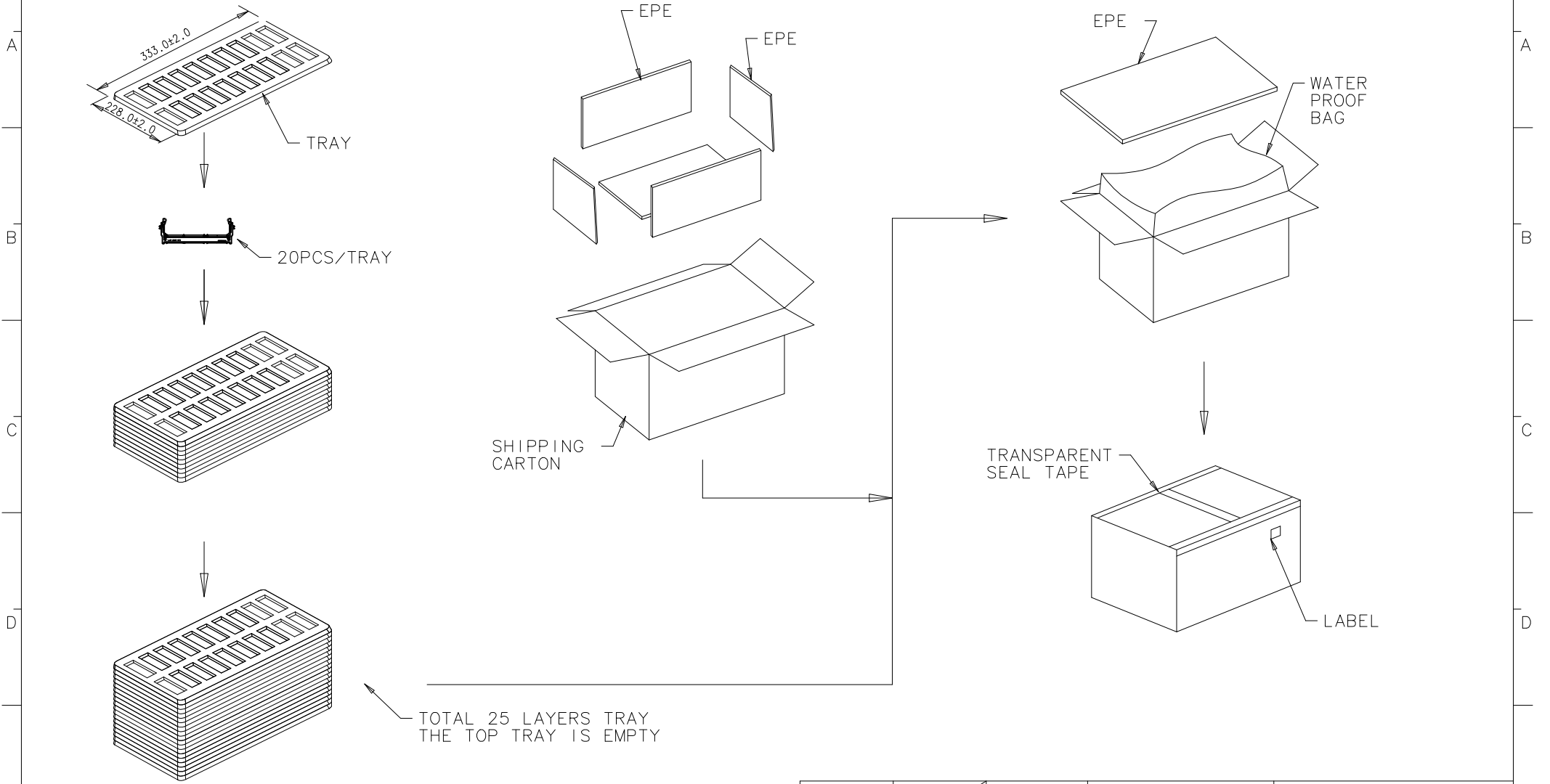
RECOMMEND P.C.B. LAYOUT

SDRAM VARIATIONS	DIM B	DIM C
TYPE 1	30.4	42.4
TYPE 2	36.7	48.7
TYPE 3	35.0	47.0

X. ± 0.25	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±		DDRIII SO DIMM CONNECTOR	
.XX ± 0.05	.XX° ±	MAT'L	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8RN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1997
Q·TY			DR: Wang Justin 2/24'14	SCALE SHEET REV.
				N/A 3/5 G

IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND.

REV.	ECN. NO.	APPD.



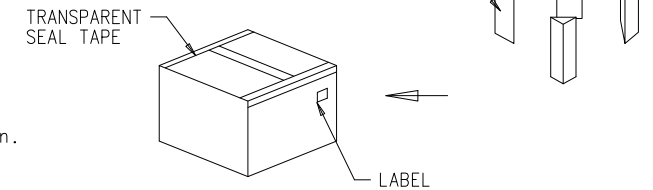
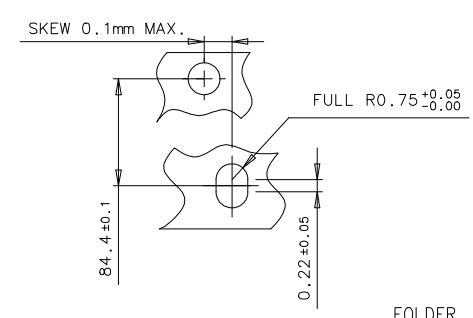
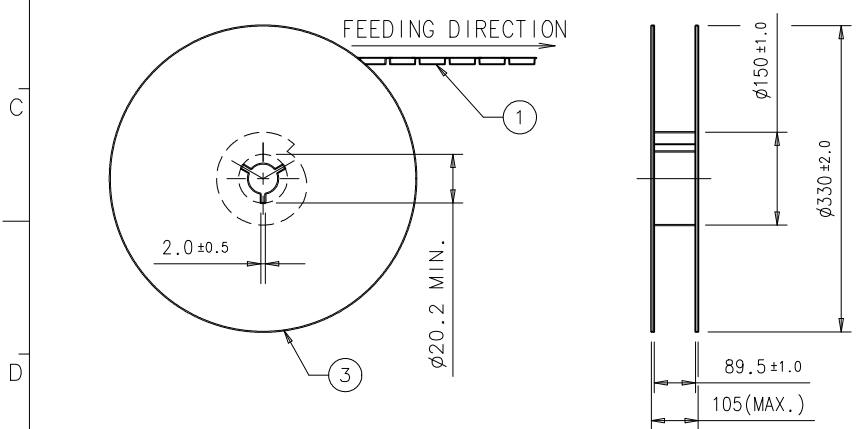
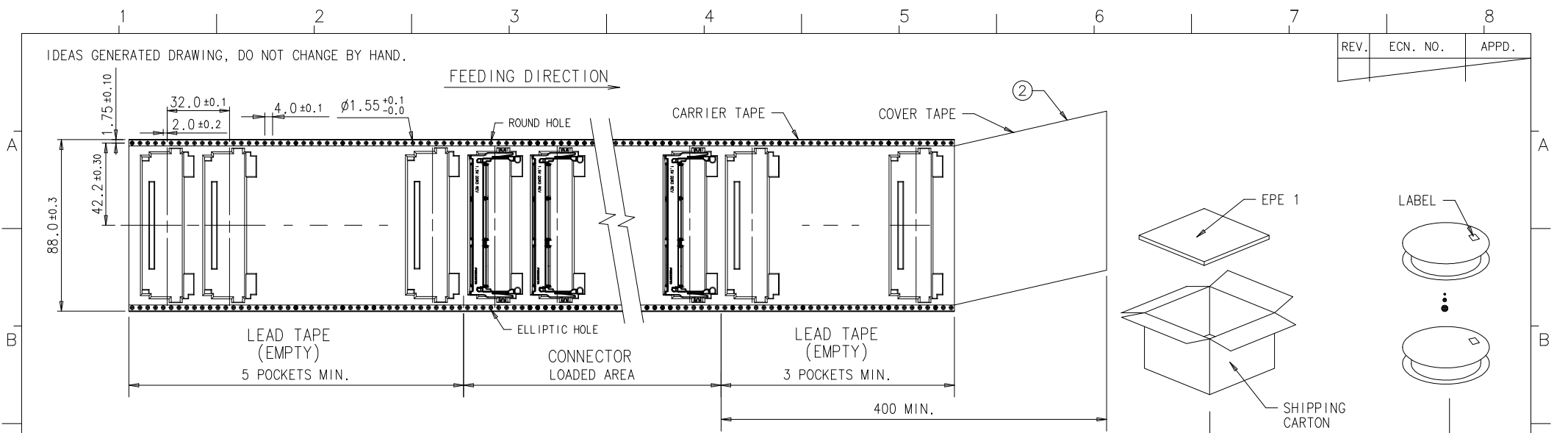
NOTES:  
1. PACKING CAPACITY : 20 PCS/TRAY, 24 TRAYS/BOX,  
TOTAL 480 PCS/BOX.

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 1.0	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.XX ± 0.5	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
.XXX ±	.XXX° ±		AS0A62*-H8RN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1997
			DR: Wang Justin 2/24'14	SCALE SHEET REV. N/A 4/5 G

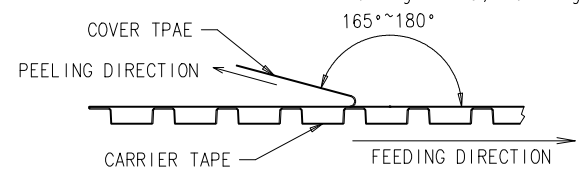
CONNECTOR P/N	AS0A62*-H8RN-4H
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REV.	ECN. NO.	APPD.



- NOTES:
1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.
  2. COVER TAPE PEELING STRENGTH : 0.01kgf MIN., 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 140 PCS/REEL, 3 REELS/BOX, TOTAL 420 PCS/BOX.

③	REEL	POLYSTYRENE
②	COVER TAPE	POLYESTER
①	CARRIER TAPE	POLYSTYRENE
ITEM	DESCRIPTION	MATERIAL

X. ± 1.5	X° ±	UNITS mm	NAME (INTENDED USE)	<b>FOXCONN®</b>
.X ± 1.0	.X° ±	MAT'L	DDR III SO DIMM CONNECTOR	
.XX ± 0.5	.XX° ±	FINISH	PART NO. (INTENDED USE)	CLASS: □CONFIDENTIAL □SECRET ■GENERAL
.XXX ±	.XXX° ±		ASOA62*-H8RN-*H	TITLE: CUSTOMER DRAWING
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			CHKD: ZH Wang	317-0000-1997
QTY			DR: Wang Justin 2/24/14	SCALE SHEET REV.
				N/A 5/5 G

CONNECTOR P/N	ASOA62*-H8RN-7H
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